

Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	Utility
Title::	Recessed-Bond Semiconductor Package
	Substrate
Attorney Docket Number::	TI-35932 (1962-07400)
Suggested Drawing Figure::	1
Total Drawing Sheets::	4
Small Entity?::	No

Applicant Information

Applicant Authority type::	Inventor
Primary Citizenship Country::	Philippines
Status::	Full Capacity
Given Name::	Edgardo R.
Family Name::	HORTALEZA
City of Residence::	Garland
State or Province of Residence::	TX
Country of Residence::	US
Street of mailing address::	706 Yaupon Drive
City of mailing address::	Garland
State or Province of mailing address::	TX
Country of mailing address::	US
Postal or Zip Code of mailing address::	75044

Applicant Authority type::	Inventor
Primary Citizenship Country::	US
Status::	Full Capacity
Given Name::	Gregory E.
Family Name::	HOWARD

City of Residence:: Dallas
 State or Province of Residence:: TX
 Country of Residence:: US
 Street of mailing address:: 3554 Waldorf Drive
 City of mailing address:: Dallas
 State or Province of
 mailing address:: TX
 Country of mailing address:: US
 Postal or Zip Code of
 mailing address:: 75229

Correspondence Information

Correspondence Customer Number:: 23494

Representative Information

Representative Customer Number:: 23494

DOMESTIC PRIORITY INFORMATION

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Non-Provisional of	60/456,708	03/21/03

Assignee Information

Assignee name:: Texas Instruments Incorporated
 Street of mailing address:: P.O. Box 655474, MS 3999
 City of mailing address:: Dallas
 State or Province of
 mailing address:: TX
 Country of mailing
 address:: US
 Postal or Zip Code of
 mailing address:: 75265